



Material Content Data Sheet



Sales Product Name	TLE4247EL30			Issued	29. August 2013			
MA#	MA001107872							
Package	PG-DSO-8-27			Weight*	83.91 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.803	2.15	2.15	21491	21491
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.728	0.87		8672	
wire	non noble metal	copper	7440-50-8	29.548	35.21	36.13	352117	361331
	noble metal	gold	7440-57-5	0.066	0.08	0.08	787	787
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1184
plastics	plastics	epoxy resin	-	4.569	5.44		54444	
	inorganic material	silicondioxide	60676-86-0	44.991	53.62	59.18	536152	591780
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8284	8284
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8634	8634
glue	plastics	epoxy resin	-	0.161	0.19		1923	
	noble metal	silver	7440-22-4	0.484	0.58	0.77	5770	7693
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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